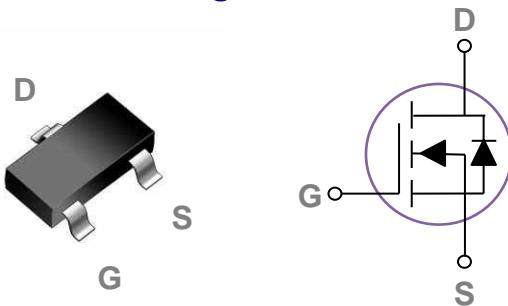


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOT23-3S Pin Configuration



BVDSS	RDS(ON)	ID
30V	41mΩ	5A

### Features

- 30V, 5A,  $RDS(ON) = 41m\Omega @ VGS = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- MB / VGA / Vcore
- Load Switch
- Hand-Held Instrument

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D$	Drain Current – Continuous ( $T_A=25^\circ C$ )	5	A
	Drain Current – Continuous ( $T_A=70^\circ C$ )	4	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	20	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	9	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	13.4	A
$P_D$	Power Dissipation ( $T_A=25^\circ C$ )	1.56	W
	Power Dissipation – Derate above $25^\circ C$	12.5	$mW/^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	80	$^\circ C/W$

**Electrical Characteristics ( $T_J=25\text{ }^{\circ}\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	30	---	---	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=30\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	$\mu\text{A}$
		$V_{DS}=24\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=100\text{ }^{\circ}\text{C}$	---	---	10	$\mu\text{A}$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 12\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$

**On Characteristics**

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$ , $I_D=2\text{A}$	---	34	41	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=1\text{A}$	---	41	50	$\text{m}\Omega$
		$V_{GS}=2.5\text{V}$ , $I_D=0.8\text{A}$	---	62	85	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	0.5	0.8	1.2	V

**Dynamic and switching Characteristics**

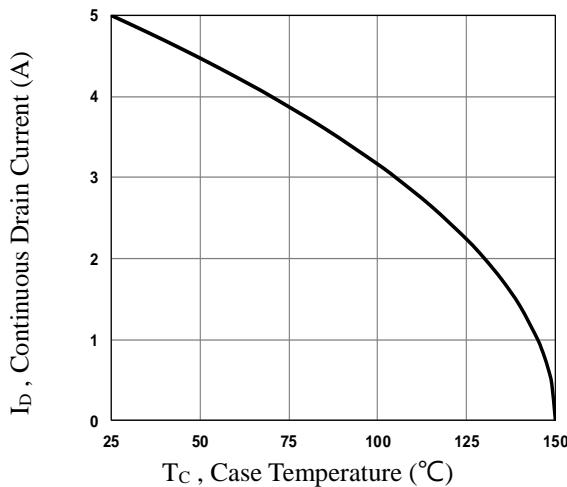
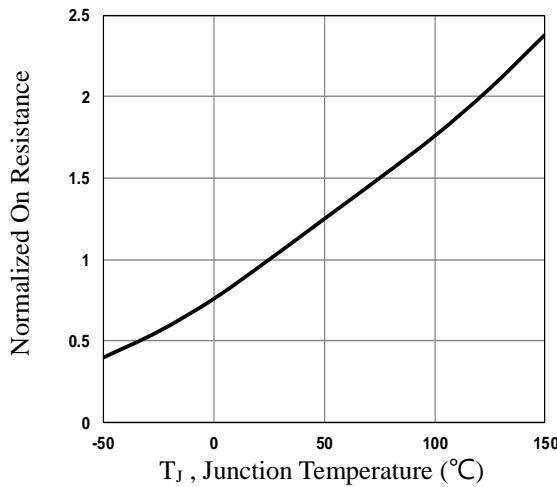
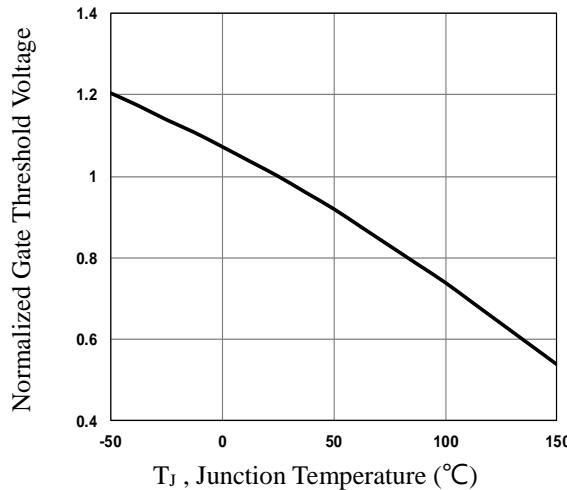
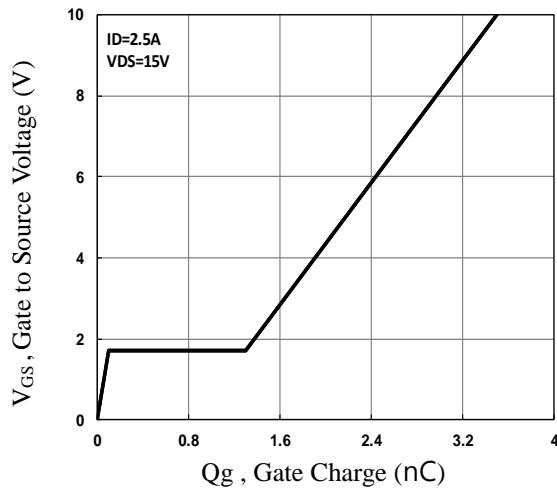
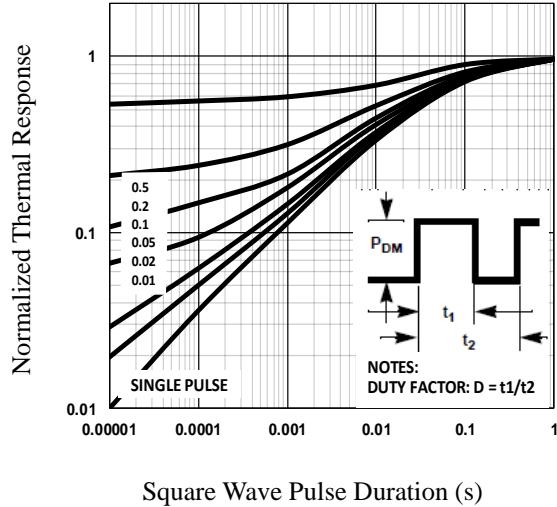
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{DS}=15\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=2.5\text{A}$	---	3.5	6	nC
$Q_{gs}$	Gate-Source Charge <sup>3, 4</sup>		---	0.1	0.2	
$Q_{gd}$	Gate-Drain Charge <sup>3, 4</sup>		---	1	1.5	
$T_{d(on)}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{DS}=15\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=6\Omega$ $I_D=2.5\text{A}$	---	6	9	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	9	13	
$T_{d(off)}$	Turn-Off Delay Time <sup>3, 4</sup>		---	33	50	
$T_f$	Fall Time <sup>3, 4</sup>		---	4	6	
$C_{iss}$	Input Capacitance	$V_{DS}=15$ , $V_{GS}=0\text{V}$ , $F=1\text{MHz}$	---	240	360	pF
$C_{oss}$	Output Capacitance		---	40	60	
$C_{rss}$	Reverse Transfer Capacitance		---	30	45	
$R_g$	Gate resistance	$V_{GS}=0\text{V}$ , $V_{DS}=0\text{V}$ , $F=1\text{MHz}$	---	1	---	$\Omega$

**Drain-Source Diode Characteristics and Maximum Ratings**

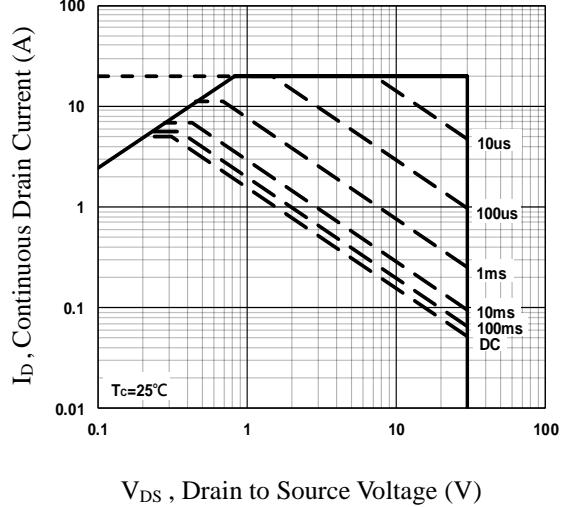
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	5	A
$I_{SM}$	Pulsed Source Current		---	---	10	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	V
$t_{rr}$	Reverse Recovery Time	$V_R=30\text{V}$ , $I_s=2.5\text{A}$	---	150	---	ns
$Q_{rr}$	Reverse Recovery Charge	$di/dt=100\text{A}/\mu\text{s}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	270	---	nC

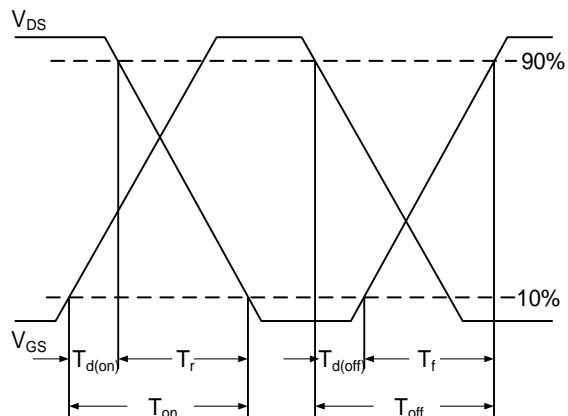
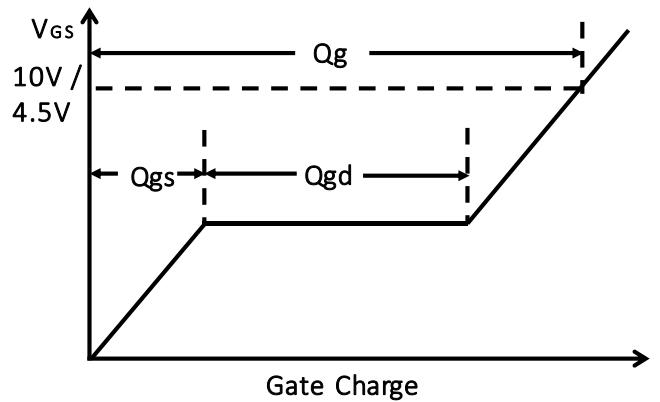
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25\text{V}$ ,  $V_{GS}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{AS}=13.4\text{A}$ ,  $R_G=25\Omega$ , Starting  $T_J=25\text{ }^{\circ}\text{C}$ .
3. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

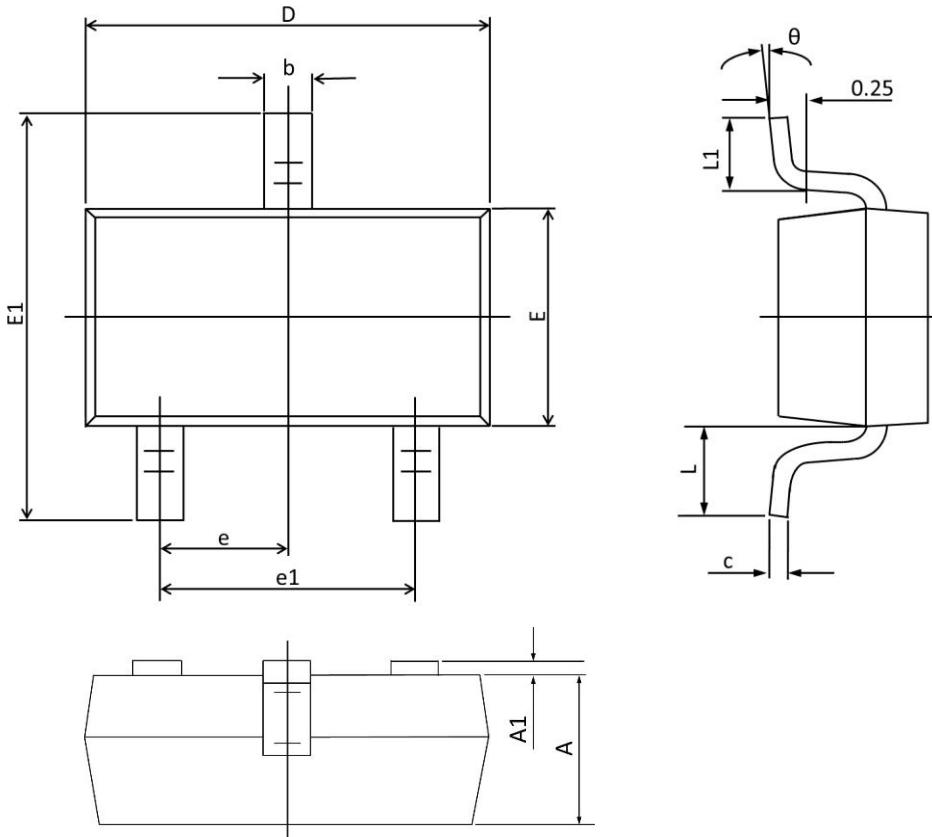

**Fig.1 Continuous Drain Current vs.  $T_c$** 

**Fig.2 Normalized RD<sub>SON</sub> vs.  $T_J$** 

**Fig.3 Normalized  $V_{th}$  vs.  $T_J$** 

**Fig.4 Gate Charge Waveform**


Square Wave Pulse Duration (s)

**Fig.5 Normalized Transient Impedance**

**Fig.6 Maximum Safe Operation Area**


**Fig.7 Switching Time Waveform**

**Fig.8 Gate Charge Waveform**

## SOT23-3S PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.001	0.100	0.000	0.004
b	0.300	0.500	0.012	0.020
c	0.080	0.180	0.003	0.008
D	2.700	3.100	0.106	0.122
E	1.100	1.500	0.043	0.059
E1	2.100	2.640	0.080	0.104
e	0.950 TYP.		0.037 TYP.	
e1	1.780	2.040	0.070	0.080
L	0.550 REF.		0.022 REF.	
L1	0.100	0.500	0.004	0.020
theta	1°	10°	1°	10°